

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg	
Die	Doped silicon	Silicon (Si)	7440-21-3	0.24	100.0	5.1	
		Subtotal		0.24	100	5.1	
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01	0.03	0.12	
		Iron (Fe)	7439-89-6	0.02	0.1	0.4	
		Copper (Cu)	7440-50-8	18.69	99.87	399.48	
		Subtotal		18.72	100	400	
Heat Spreader	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	0.36	
		Iron (Fe)	7439-89-6	0.06	0.1	1.2	
		Copper (Cu)	7440-50-8	56.06	99.87	1198.44	
		Subtotal		56.14	100	1200	
Isolator	Copper alloy	Phosphorous (P)	7723-14-0	0	0.1	0.09	
		Aluminium Trioxide (Al2O3)	1344-28-1	3.86	91.6	82.44	
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.04	0.9	0.81	
		Molybdenum (Mo)	7439-98-7	0.29	7.0	6.3	
		Manganese (Mn)	7439-96-5	0.02	0.4	0.36	
		Subtotal		4.21	100	90	
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.06	5.0	1.25	
		Silver (Ag)	7440-22-4	0.03	2.5	0.62	
		Lead (Pb)	7439-92-1	1.08	92.5	23.12	
		Subtotal		1.17	100	24.99	
Mould Compound		Bisphenol-A Bisphenol-A Diglycidyl Ether copolymer	25036-25-3	0.23	1.3	4.94	
		Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.24	7.0	26.6
		Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	2.49	14.0	53.2
		Filler	Silica fused	60676-86-0	1.07	6.0	22.8
		Carbon Black	Carbon black	1333-86-4	0.07	0.4	1.52
		Filler	Misc. Silica compounds (generic)	14808-60-7	12.44	70.0	266
			Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.23	1.3	4.94
		Subtotal		17.77	100	380	
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.26	100.0	27	
		Subtotal		1.26	100	27	
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01	100.0	0.27	
		Aluminium (Al)	7429-90-5	0.11	100.0	2.4	
		Subtotal		0.12	200	2.67	
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.34	90.0	7.2	
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0	0.5	0.04	
		Silver (Ag)	7440-22-4	0.01	2.5	0.2	
		Antimony (Sb)	7440-36-0	0.03	7.0	0.56	
		Subtotal		0.38	100	8	
Total				100.01	100	2137.76	

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